

- ZZ1 ■Install label in silkscreened box after final wash. Text shall be 8 pt font. Text shall be per Table 1
- ZZ2 ■These assemblies are ESD sensitive, ESD precautions shall be observed.
- ZZ3 ■These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.
- ZZ4 ■These assemblies must comply with workmanship standards IPC-A-610 Class 2., unless otherwise specified.

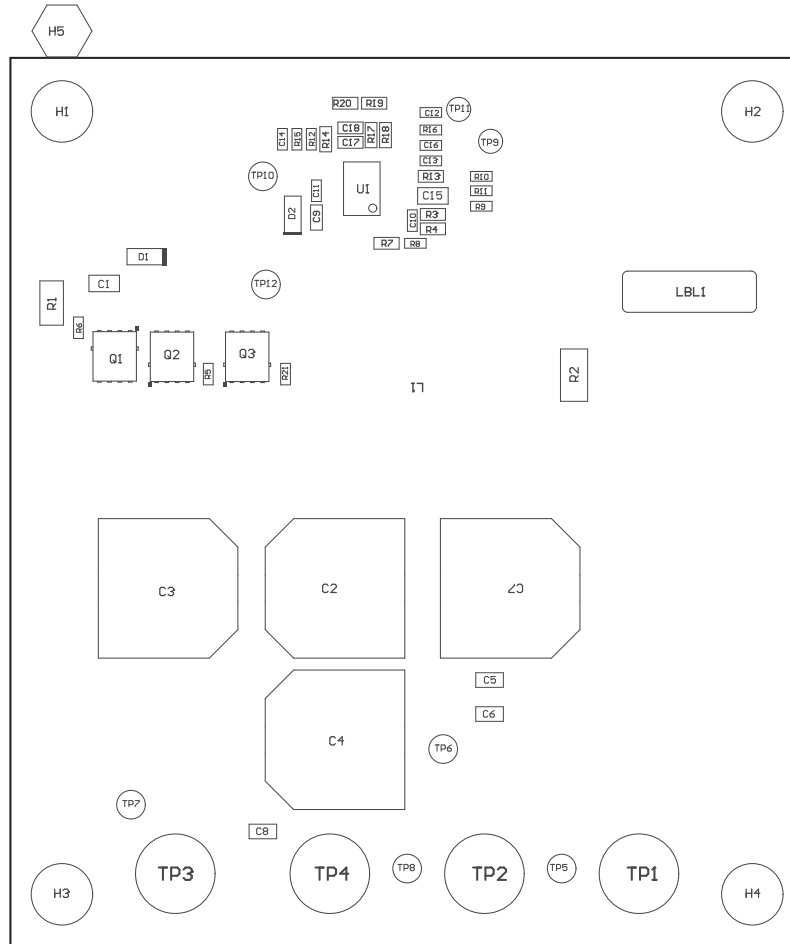
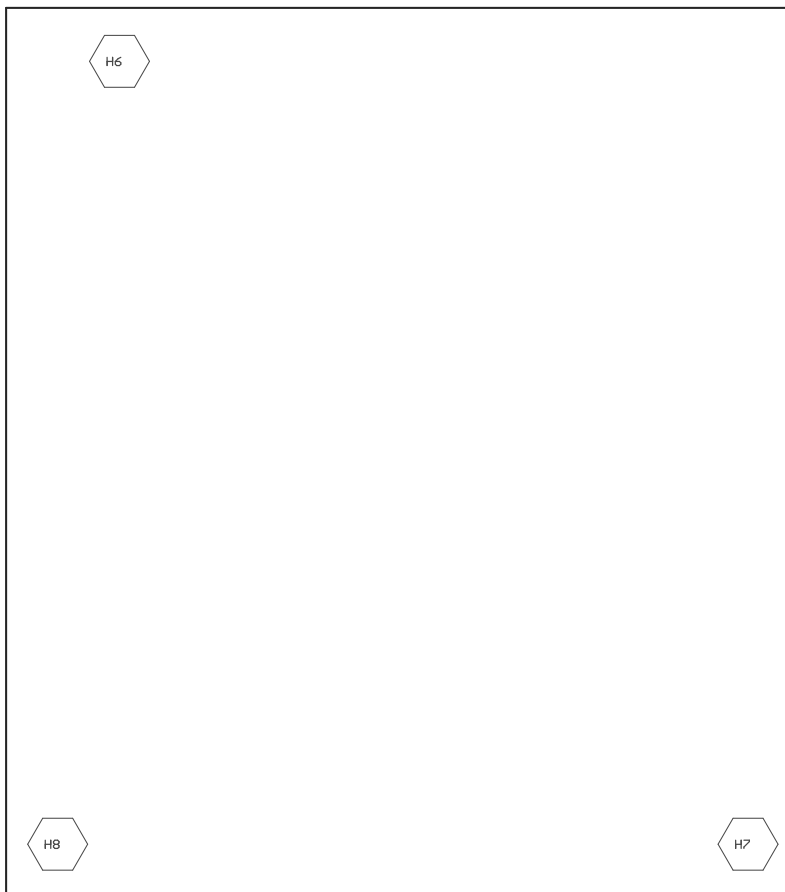


TABLE 1

Variant	Label text
001	ChangeMe!
002	ChangeMe!

COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED, AND MAY NOT BE IN BILL OF MATERIALS
ASSEMBLY VARIANT: [No Variations]

PCB VIEWED FROM TOP SIDE	BOARD #: PMP21277	REV: A	SUN REV: Not In VersionControl
IGNORE ->			
PLOT NAME = Top Assembly Drawing	GENERATED : 12/1/2017 2:33:14 PM	TEXAS INSTRUMENTS	



COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED, AND MAY NOT BE IN BILL OF MATERIALS
 ASSEMBLY VARIANT: [No Variations]

PCB VIEWED FROM BOTTOM SIDE	BOARD #: PMP21277	REV: A	SUN REV: Not In VersionControl
IGNORE ->			
PLOT NAME = Bottom Assembly Drawing	GENERATED : 12/1/2017	2:33:15 PM	TEXAS INSTRUMENTS

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